

**Amendments to the Specification:**

Please replace the paragraph beginning at page 1, line 4, with the following rewritten paragraph:

- 5     — The present invention relates to an integrated circuit package having a  
resistant layer for stopping flowed glue~~central leads~~, and more particularly to an  
integrated circuit package which may be conveniently manufactured with reduced  
manufacturing costs. —

10     Please replace the two paragraphs beginning at page 1, line 8, with the  
following rewritten paragraphs:

- Referring to FIG. 1, a conventional integrated circuit package having  
central leads includes a substrate 10, a glue layer 12, an integrated circuit 14, a  
plurality of wires 16, and a compound layer 18. The substrate 10 has an upper  
surface 20, a lower surface 22 and a long slot 24 penetrating from the upper  
15     surface 20 to the lower surface 22, wherein the lower surface 22 of the substrate  
10 is formed with wiring regions 26 arranged at the two sides of the long slot 24,  
and the wiring region 26 is formed with ~~connected~~ connection points 28. The glue  
layer 12 is coated on the upper surface 20 of the substrate 10, and is located at the  
periphery of the long slot 24. The integrated circuit 14 has a first surface 30 and a  
20     second surface 32, wherein the central portion of the first surface 30 of the  
integrated circuit 14 is formed with bonding pads 34, while the first surface 30 of  
the substrate 10 is adhered to the glue layer 12, so ~~that as to the~~ bonding pads 34  
of the substrate 10 are exposed from the long slot 24 ~~slot 24~~. The wires are  
arranged within the long slot 24 of the substrate 10, and ~~are electrically connected~~  
25     the bonding pads 34 of the integrated circuit 14 to the ~~connected~~ connection  
points 28 of the substrate 10. The compound layer 18 is filled within the long slot  
24 ~~for protecting to protect~~ the wires.

- However, the above-mentioned integrated circuit ~~image package~~ has the  
following drawbacks. When the glue layer 12 is coated on the upper surface 20 of  
30     the substrate 10, the flowed glue of the glue layer 12 ~~is covered on~~ covers the  
wiring region 26 through the long slot 24 of the substrate 10, so that the ~~connected~~

connection points 28, which are arranged at the wiring region 26, are covered by the flowed glue. —

Please replace the four paragraphs beginning at page 2, line 9, with the  
5 following rewritten paragraphs:

— An object of the present invention is to provide an integrated circuit package, which is capable of preventing the flowed glue of the glue layer from  
~~covered~~covering the wiring region, so that the wire bonding is easy.

Another object of the present invention is to provide an integrated circuit  
10 package ~~having central leads~~, which may be conveniently manufactured with reduced manufacturing costs.

To achieve the above-mentioned objects, the present invention provides an integrated circuit package ~~having central leads~~ ~~includes~~ including a substrate, a glue layer, an integrated circuit, a plurality of wires, and a first compound layer.  
15 The substrate has an upper surface, a lower surface, and ~~—, and~~ a long slot penetrating from the upper surface to the lower surface, wherein the lower surface is ~~forming~~ formed with wiring regions arranged at the two sides of the long slot, and the wiring regions are ~~forming~~ formed with a plurality of ~~connected~~ connection points. The resistant layer is coated on and in contact with the lower  
20 surface of the substrate, and is located between the long slot and the wiring region. The glue layer is coated on the upper surface of the substrate and arranged at the periphery of the long slot. The integrated circuit has a first surface ~~forming~~ formed with a plurality of bonding pads and a second surface, wherein the first surface is adhered to the glue layer, ~~then and~~ the bonding pads are exposed from  
25 the long slot of the substrate. The wires, each of which is arranged within the long slot of the substrate, ~~and is electrically connected~~ connect the bonding pads of the integrated circuit to the ~~connected~~ connection points of the substrate, respectively. The first compound layer is filled within the long slot of the substrate ~~for to~~ protecting the ~~each~~ wires.

30 Utilizing the resistant layer to prevent the flowed glue from covering the  
~~covered~~ ~~the~~ ~~connected~~ connection points may easily achieve the objects and

functions of the invention. —

Please replace the two paragraphs beginning at page 3, line 14, with the following rewritten paragraphs:

5       -- FIG. 2 is a cross-sectional view showing an integrated circuit package having central leads of the present invention.

FIG. 3 is a top-view of showing the substrate of the present invention. --

10       Please replace the eight paragraphs beginning at page 3, line 18, with the following rewritten paragraphs:

-- Referring to FIG. 2, an integrated circuit package having central leads of the present invention includes a substrate<sub>40</sub>, a resistant layer<sub>42</sub>, a glue layer<sub>44</sub>, an integrated circuit<sub>46</sub>, a plurality of wires<sub>47</sub>, a first compound layer<sub>48</sub>, and a second compound layer<sub>50</sub>.

15       The substrate<sub>40</sub> has an upper surface<sub>52</sub>, a lower surface<sub>54</sub>, and a long slot 56 penetrating from the upper surface<sub>52</sub> to the lower surface<sub>54</sub>. The lower surface<sub>54</sub> of the substrate<sub>40</sub> is formed with wiring regions<sub>58</sub> arranged at the two sides of the long slot<sub>56</sub>, and the wiring regions<sub>58</sub> are formed with a plurality of connected connection points<sub>60</sub>, each of which is are formed with a ball grid array. Please referring to FIG. 3, the length of the wiring region 60-58 is shorter than that of the long slot<sub>56</sub> of the substrate<sub>40</sub>. Therefore, while the long slot<sub>56</sub> of the substrate is drilled, the periphery of the long slot<sub>56</sub> may be cracked, so that and the flowed glue of the glue layer<sub>44</sub> can not flow to the wiring regions<sub>58</sub> via the cracked according to the resistant layer 42. The resistant layer 42 separates the  
25       long slot 56 from the wiring region 58. A length of the resistant layer 42 is substantially equal to the length of the wiring region 58.

The resistant layer<sub>42</sub> is coated on the lower surface<sub>54</sub> of the substrate<sub>40</sub>, and is located between the long slot<sub>56</sub> and the wiring region<sub>58</sub>. In preferred the embodiment, the resistant layer<sub>42</sub> is made of green.

30       The glue layer<sub>44</sub> is coated on the upper surface<sub>52</sub> of the substrate<sub>40</sub>, and is located at the periphery of the long slot<sub>56</sub>.

The integrated circuit\_46 has a first surface\_62 on which a plurality of bonding pads\_66 are formed, and a second surface\_64. The first surface\_62 is adhered to the glue layer\_44, ~~thus, and~~ the bonding pads\_66 are exposed from the long slot\_56 of the substrate\_40.

- 5        The plurality of wires\_47, each of which is arranged within the long slot\_56 of the substrate\_40, ~~and is electrically connected the bonding pads\_66 of the integrated circuit\_46 to the connected connection points\_60 of the substrate\_40.~~

The first compound layer\_48 is filled within the long slot\_56 of the substrate 40 ~~for protecting to protect the each wire\_47, respectively.~~

- 10       The second compound layer\_50 is covered on the upper surface\_52 of the substrate\_40 to ~~prevent protect~~ the integrated circuit\_46. --

Please replace the two paragraphs beginning at page 5, line 6, with the following rewritten paragraphs:

- 15       -- 1. Since if the flowed glue of the glue layer\_44 ~~is flowed flows~~ to the lower surface\_54 of the substrate\_40 through the long slot\_56, the resistant layer 42 prevents the flowed glue ~~can be prevented by the resistant layer 42 to from flowing~~ to the wiring regions\_58, so that the ~~connected connection points\_60 may not cannot be~~ covered by the flowed glue.

- 20       2. ~~Since the~~ The length of each of the wiring regions\_58 ~~are is~~ shorter than that of the long slot\_56, so that, while drilled the long slot\_56, So, if the substrate\_40 is cracked while the long slot\_56 is being drilled, which is ~~can be not coupled to the wiring regions\_58, thus the connected the connection points\_60~~ can be not covered by the flowed glue of the glue layer\_44. --

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